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## Electronic Patent Application Submission

### USPTO Use Only

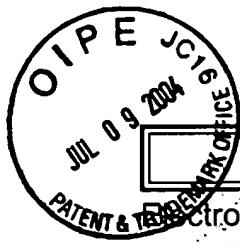
EFS ID: 64277  
 Application ID: 10766046   
 Title of Invention: LEADFRAME TYPE  
 SEMICONDUCTOR PACKAGE  
 HAVING REDUCED INDUCTANCE  
 AND ITS MANUFACTURING  
 METHOD  
 First Named Inventor: GI KIM  
 Domestic/Foreign Application: Domestic Application  
 Filing Date: 2004-01-28  
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 Submission Type: Information Disclosure Statement  
 Filing Type:  
 Confirmation number: 2288  
 Attorney Docket Number: AMKOR099A

Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark

Office,ou=Department of Commerce,o=U.S. Government,c=US

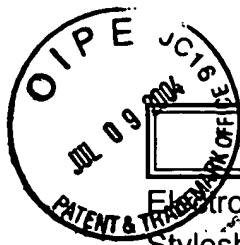
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## TRANSMITTAL

Electronic Version v1.1  
Stylesheet Version v1.1.0

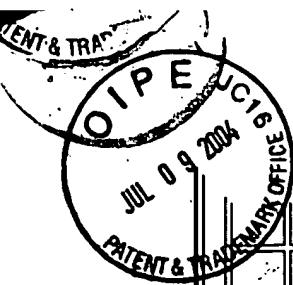
Title of Invention	LEADFRAME TYPE SEMICONDUCTOR PACKAGE HAVING REDUCED INDUCTANCE AND ITS MANUFACTURING METHOD	
Application Number:	10/766046	
Date:	2004-01-28	
First Named Applicant:	GI JEONG KIM	
Confirmation Number:	2288	
Attorney Docket Number:	AMKOR099A	
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Submitted by:	Elec. Sign.	Sign. Capacity
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney
Documents being submitted	Files	
us-ids	ids3-usidst.xml us-ids.dtd us-ids.xsl	
Comments		



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18  
Stylesheet Version v18.0

Title of Invention.	LEADFRAME TYPE SEMICONDUCTOR PACKAGE HAVING REDUCED INDUCTANCE AND ITS MANUFACTURING METHOD						
Application Number:	10/766046						
Confirmation Number:	2288						
First Named Applicant:	GI KIM						
Attorney Docket Number:	AMKOR099A						
Art Unit:	2613						
Search string:	( 5608265 or 5608267 or 5625222 or 5633528 or 5639990 or 5640047 or 5641997 or 5643433 or 5644169 or 5646831 or 5650663 or 5661088 or 5665996 or 5673479 or 5683806 or 5689135 or 5696666 or 5701034 or 5703407 or 5710064 or 5724233 or 5723899 or 5726493 or 5736432 or 5745984 or 5753532 or 5753977 or 5766972 or 5770888 or 5776798 or 5783861 or 5801440 or 5814877 or 5814881 or 5814883 or 5814884 or 5817540 or 5818105 or 5821457 or 5821615 or 5834830 or 5835988 or 5844306 or 5856911 or 5859471 or 5866939 or 5871782 or 5874784 or 5877043 or 5886397 ).pn.						
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Signature

Examiner Name	Date